

Electronic Patent Application Fee Transmittal

Application Number:	10810965
Filing Date:	26-Mar-2004
Title of Invention:	Novel method to improve bump reliability for flip chip device
First Named Inventor/Applicant Name:	Yen-Ming Chen
Filer:	Daniel R. McClure
Attorney Docket Number:	TS01-0413C

Filed as Large Entity

Utility Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Filing a brief in support of an appeal	1402	1	500	500
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				500